## What is claimed is:

1. A heatsink for an electronic component comprising:
a plurality of heatsink plates, each of the heatsink plates having a binding portion and a heat-dissipating portion, each heat-dissipating portion including a plurality of heat-dissipating fins joined to the binding portion, wherein the heatsink plates are bound together at the binding portions to form a heat-absorbing portion for contacting a heat-dissipating surface of an electronic component, and at least some of the heat-dissipating portions of the heatsink plates are bent at angles relative to the respective binding portions of the heatsink plates to increase separation between adjacent heat-dissipating portions; and

means for binding the plurality of heatsink plates together, wherein the plurality of heat-dissipating fins on each heat-dissipating portion are grouped into at least two groups of fins and the groups are separated from each other for mounting of the heatsink on an electronic component with a clip fitting on the electronic component between the groups of the fins.

- 2. The heatsink of claim 1, wherein each heat-dissipating portion of an individual heatsink plate has one protrusion which contacts an adjacent heat-dissipating plate so that each heat-dissipating plate is displaced at an angle from adjacent heat-dissipating plates in the heatsink.
- 3. The heatsink of claim 1, wherein the binding portions of individual heatsink plates have at least one pair of a protrusion and an indentation which are complementary and engaged with a protrusion and an indentation, respectively, of another heatsink plate for maintaining registration of and preventing distortion of the binding portions.
- 4. The heatsink of claim 2, wherein the binding portions of the individual heatsink plates have at least one pair of a protrusion and an indentation which are complementary and engaged with a protrusion and an indentation, respectively, of another heatsink plate for maintaining registration of and preventing distortion of the binding portions.
- 5. The heatsink of claim 1, comprising a plurality of spacers, each spacer being interposed between the binding portions of a respective pair of neighboring

heatsink plates, wherein the spacers have extensions extending from the plurality of binding portions.

- 6. The heatsink of claim 5, wherein each heat-dissipating portion of an individual heatsink plate has one protrusion which contacts an adjacent heat-dissipating plate so that each heat-dissipating plate is displaced at an angle from adjacent heat-dissipating plates in the heatsink.
- 7. The heatsink of claim 5, wherein the binding portions of the individual heatsink plates and the spacers have at least one pair of a protrusion and an indentation which are complementary with a protrusion and an indentation, respectively, of another heatsink plate, for preventing distortion of the binding portions.
- 8. The heatsink of claim 6, wherein the binding portions of the individual heatsink plates and the spacers have at least one pair of a protrusion and an indentation which are complementary with a protrusion and an indentation, respectively, of another heatsink plate, for preventing distortion of the binding portions.
- 9. The heatsink of claim 1/comprising a fan installed at the heatsink to blow air over the heatsink.
- 10. The heatsink of claim 2, comprising a fan installed at the heatsink to blow air over the heatsink.
- 11. The heatsink of claim 3, comprising a fan installed at the heatsink to blow air over the heatsink.
- 12. The heatsink of claim 1, comprising a bracket and a fan fitted to the bracket, to blow air over the heatsink.
- 13. The heatsink of claim 2, comprising a bracket and a fan fitted to the bracket, to blow air over the heatsink.
- 14. The heatsink of claim 3, comprising a bracket and a fan fitted to the bracket, to blow air over the heatsink.

15. A heatsink for an electronic component comprising:

a plurality of heatsink plates, each of the heatsink plates having a binding portion and a heat-dissipating portion, each heat-dissipating portion including a plurality of heat-dissipating fins joined to the binding portion, wherein the heatsink plates are bound together at the binding portions to form a heat-absorbing portion for contacting a heat-dissipating surface of an electronic component, and at least some of the heat-dissipating portions of the heatsink plates are bent at angles relative to the respective binding portions of the heatsink plates to increase separation between adjacent heat-dissipating portions; and

means for binding the plurality of heatsink plates together, wherein each heatdissipating fin in the heat-dissipating portion has a protrusion contacting an adjacent heat-dissipating fin and displacing the heat-dissipating plate from the adjacent heatdissipating plate.

- 16. The heatsink of claim 15 wherein the plurality of heat-dissipating fins on each heat-dissipating portion are grouped into at least two groups of fins and the groups are separated from each other for mounting of the heatsink on an electronic component with a clip fitting on the electronic component between the groups of the fins.
- 17. The heatsink of claim 15, wherein the binding portions of individual heatsink plates have at least one pair of a protrusion and an indentation which are complementary and engaged with a protrusion and an indentation, respectively, of another heatsink plate for maintaining registration of and preventing distortion of the binding portions.
- 18. The heatsink of claim 15, comprising a plurality of spacers, each spacer being interposed between the binding portions of a respective pair of neighboring heatsink plates, wherein the spacers have extensions extending from the plurality of binding portions.
- 19. The heatsink of claim 18, wherein each heat-dissipating portion of an individual heatsink plate has one protrusion which contacts an adjacent heat-dissipating plate so that each heat-dissipating plate is displaced at an angle from adjacent heat-dissipating plates in the heatsink.

20. The heatsink of claim 18, wherein the binding portions of the individual heatsink plates and the spacers have at least one pair of a protrusion and an indentation which are complementary with a protrusion and an indentation, respectively, of another heatsink plate, for preventing distortion of the binding portions.

## 21. A heatsink for an electronic component comprising:

a plurality of heatsink plates, each of the heatsink plates having a binding portion and a heat-dissipating portion, each heat-dissipating portion including a plurality of heat-dissipating fins joined to the binding portion, wherein the heatsink plates are bound together at the binding portions to form a heat-absorbing portion for contacting a heat-dissipating surface of an electronic component, and at least some of the heat-dissipating portions of the heatsink plates are bent at angles relative to the respective binding portions of the heatsink plates to increase separation between adjacent heat-dissipating portions; and

means for binding the plurality of heatsink plates together, wherein each heatdissipating portion of an individual heatsink plate has one protrusion which contacts an adjacent heat-dissipating plate so that each heat-dissipating plate is displaced at an angle from adjacent heat-dissipating plates in the heatsink.

## 22. A heatsink for an electronic component comprising:

a plurality of heatsink plates, each of the heatsink plates having a binding portion and a heat-dissipating portion, each heat-dissipating portion including a plurality of heat-dissipating fins joined to the binding portion, wherein the heatsink plates are bound together at the binding portions to form a heat-absorbing portion for contacting a heat-dissipating surface of an electronic component, and at least some of the heat-dissipating portions of the heatsink plates are bent at angles relative to the respective binding portions of the heatsink plates to increase separation between adjacent heat-dissipating portions; and

means for binding the plurality of heatsink plates together, wherein the binding portions of individual heatsink plates have at least one pair of a protrusion and an indentation which are complementary and engaged with a protrusion and an indentation, respectively, of another heatsink plate for maintaining registration of and preventing distortion of the binding portions.

23. A heatsink for an electronic component comprising:

a plurality of heatsink plates, each of the heatsink plates having a binding portion and a heat-dissipating portion, each heat-dissipating portion including a plurality of heat-dissipating fins joined to the binding portion, wherein the heatsink plates are bound together at the binding portions to form a heat-absorbing portion for contacting a heat-dissipating surface of an electronic component, and at least some of the heat-dissipating portions of the heatsink plates are bent at angles relative to the respective binding portions of the heatsink plates to increase separation between adjacent heat-dissipating portions;

means for binding the plurality of heatsink plates together; and a plurality of spacers, each spacer being interposed between the binding portions of a respective pair of neighboring heatsink plates, wherein the spacers have extensions extending from the plurality of binding portions.